



CBR-SMD RF C0G, Ceramic, 3.9 pF, +/-0.25 pF, 25 VDC, C0G, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

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Т	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	62.5 VDC
В	0.25mm +0.05/-0.1mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.209%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/De
Packaging Quantity	10000	Insulation Resistance	10 GOhms
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Specifications	
Capacitance	3.9 pF
Tolerance	+/-0.25 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.209%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	478

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